

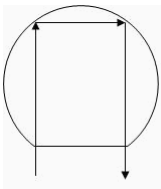
Part Number

Customer

Category		Parameter	Specification	Measurement Method
OverallWafer	1.0	Diameter	100.00 +/- 0.50 mm	
	2.0	Primary Flat Orientation	{110} +/- 1 degree	Wafer Vendor
	3.0	Primary Flat Length	32.50 +/- 2.50 mm	Wafer Vendor
	4.0	Secondary Flat Orientation	none	
	5.0	Secondary Flat Length	none / 18.5mm +/-2.5mm	Wafer Vendor
	6.0	Overall Thickness	317.00 +/- 11.00 µm	ADE, 100%
	7.0	Total Thickness Variation (TTV)	<5.00µm	ADE 100% to ASTM F534
	8.0	Bow	<60.00µm	ADE to ASTM F534, 20%
	9.0	Warp	<60.00µm	ADE to ASTM F657, 20%
	10.0	Edge Chips	0	Bright Light, 100% (note 2)
	11.0	Edge Exclusion	5mm	
HandleSilicon	12.0	Handle Growth Method	CZ	Wafer Vendor
	13.0	Handle Orientation	{100} +/- 0.5 degree	Wafer Vendor
	14.0	Handle Thickness	300.00 +/- 10.00 µm	ADE, 100%
	15.0	Handle Doping Type	N	Wafer Vendor
	16.0	Handle Dopant	Phosphorus	Wafer Vendor
	17.0	Handle Resistivity	1- 10 Ohm-cm	Wafer Vendor
	18.0	Backside Finish	Polished with lasermark and light handling marks. 2um oxide (approximate - back oxide not measured).	
BuriedOxide	19.0	Oxide Type	Thermal	
	20.0	Oxide Thickness	20,000.00 +/- 1,000.00 A	Centre point measurement, 4%
	21.0	Oxide formed on	Handle Wafer	
DeviceSilicon	22.0	Device Growth Method	CZ	Wafer Vendor
	23.0	Device Orientation	{100} +/- 0.5 degree	Wafer Vendor
	24.0	Nominal Thickness	15.00 +/- 0.50 µm	Filmetrics, 100% 9-Pt (note3)
	25.0	Distance to device silicon edge from wafer edge	<= 2mm	Typical by Process
	26.0	Device Doping Type	N	Wafer Vendor
	27.0	Device Dopant	Phosphorous	Wafer Vendor
	28.0	Device Resistivity	0.01 - 0.02 Ohm-cm	Wafer Vendor
	29.0	Voids	none	Bright Light, 100% (note2)
	30.0	Scratches	0	Bright Light, 100% (note 2)
	31.0	Haze	none	Bright Light, 100% (note 2)
	32.0	LPD Count	<30 @0.3um	Tencor Particle Counter

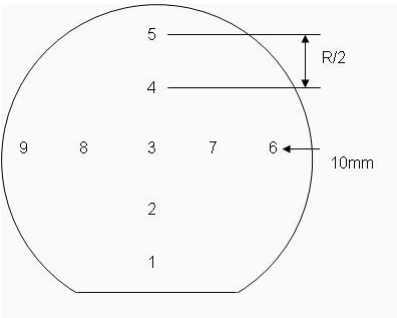
Part Number	Customer
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Shipping Details	Wafer per box :	Max 25	
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 100.00mm Antistatic Double Bagging	
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness	
Explanatory Notes	1. Microscope inspection performed using microscope scan as below. 5x objective.		

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information